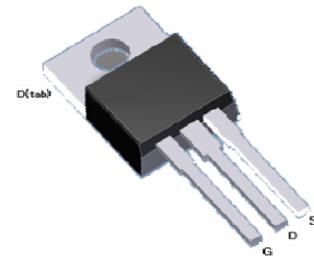
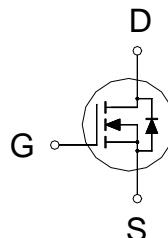


N-Channel Logic Level Enhancement Mode Field Effect Transistor
Product Summary:

BV_{DSS}	100V
$R_{DS(on)}$ (MAX.)	8.5m Ω
I_D	96A



UIS, Rg 100% Tested

Pb-Free Lead Plating & Halogen Free


ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	96	A
	$T_C = 100^\circ\text{C}$		61	
Pulsed Drain Current ¹		I_{DM}	380	
Avalanche Current		I_{AS}	15	
Avalanche Energy	$L = 0.1\text{mH}, I_{AS} = 15\text{A}, RG = 25\Omega$	E_{AS}	11.2	mJ
Repetitive Avalanche Energy ²	$L = 0.05\text{mH}$	E_{AR}	5.6	
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	138	W
	$T_C = 100^\circ\text{C}$		55	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$	0.9	62.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$			

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	100			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.0	2.0	3.0	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 12V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 80V, V_{GS} = 0V$			1	μA
		$V_{DS} = 70V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			25	
On-State Drain Current ¹	$I_{D(\text{ON})}$	$V_{DS} = 5V, V_{GS} = 10V$	96			A
Drain-Source On-State Resistance ¹	$R_{DS(\text{ON})}$	$V_{GS} = 10V, I_D = 20A$		7.1	8.5	$\text{m}\Omega$
		$V_{GS} = 4.5V, I_D = 20A$		8.4	10.5	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 20A$		70		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 50V, f = 1\text{MHz}$		4430		pF
Output Capacitance	C_{oss}			744		
Reverse Transfer Capacitance	C_{rss}			108		
Gate Resistance	R_g	$V_{GS} = 15\text{mV}, V_{DS} = 0V, f = 1\text{MHz}$		1.0		Ω
Total Gate Charge ^{1,2}	$Q_g(V_{GS}=10V)$	$V_{DS} = 50V, V_{GS} = 10V,$ $I_D = 20A$		78		nC
	$Q_g(V_{GS}=4.5V)$			44		
Gate-Source Charge ^{1,2}	Q_{gs}			13		
Gate-Drain Charge ^{1,2}	Q_{gd}			23		
Turn-On Delay Time ^{1,2}	$t_{d(\text{on})}$	$V_{DS} = 50V,$ $I_D = 20A, V_{GS} = 10V, R_{GS} = 6\Omega$		10		nS
Rise Time ^{1,2}	t_r			15		
Turn-Off Delay Time ^{1,2}	$t_{d(\text{off})}$			32		
Fall Time ^{1,2}	t_f			20		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ\text{C}$)						
Continuous Current	I_S	$I_F = 20A, V_{GS} = 0V$			96	A
Pulsed Current ³	I_{SM}				380	
Forward Voltage ¹	V_{SD}	$I_F = 20A, V_{GS} = 0V$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 20A, dI_F/dt = 100A/\mu\text{s}$		46		nS
Reverse Recovery Charge	Q_{rr}				225	

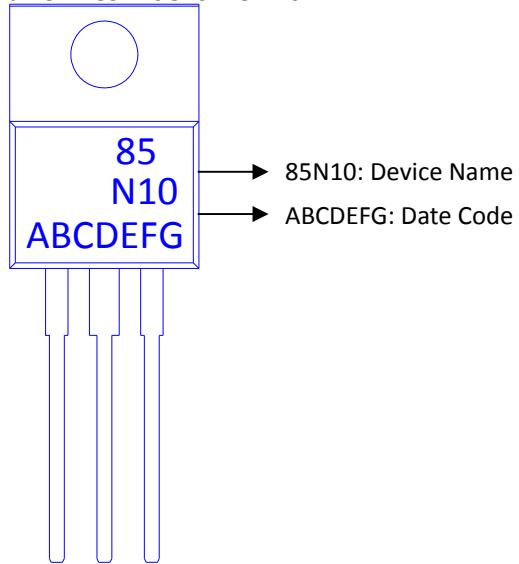
¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

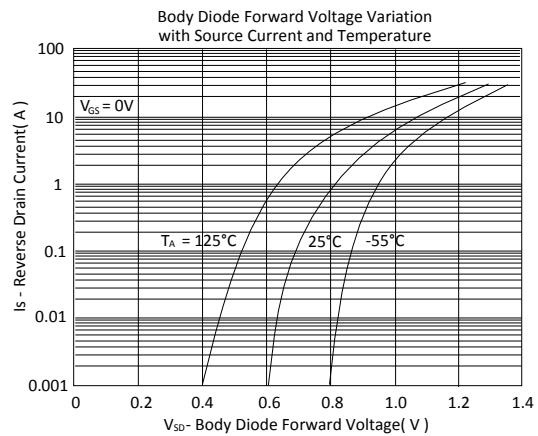
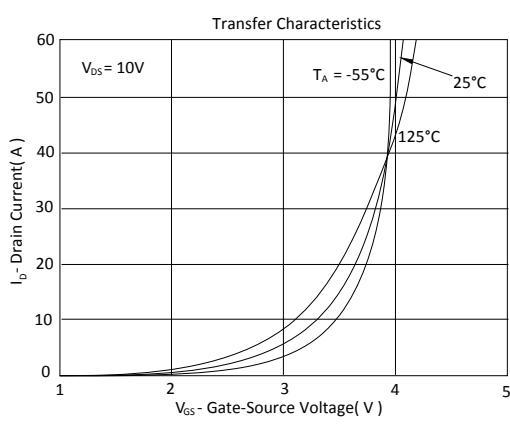
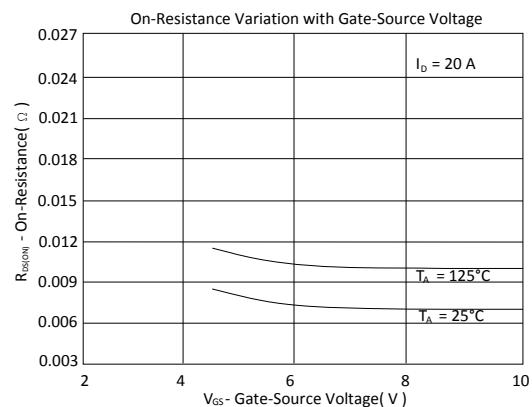
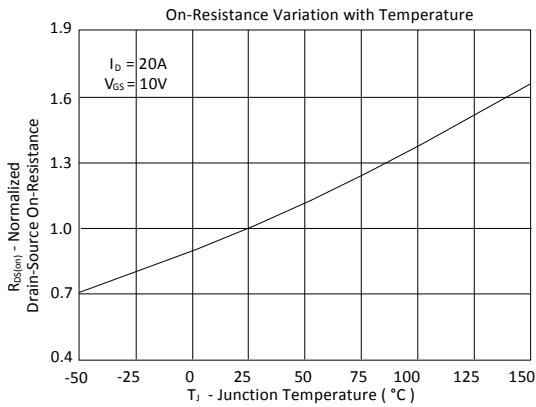
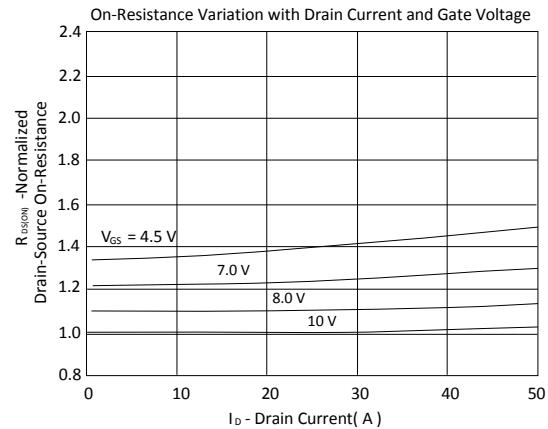
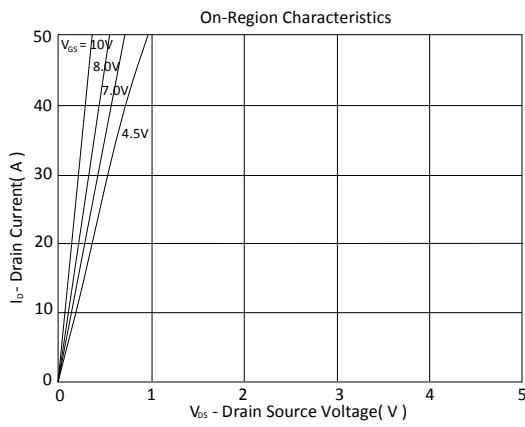
³Pulse width limited by maximum junction temperature.

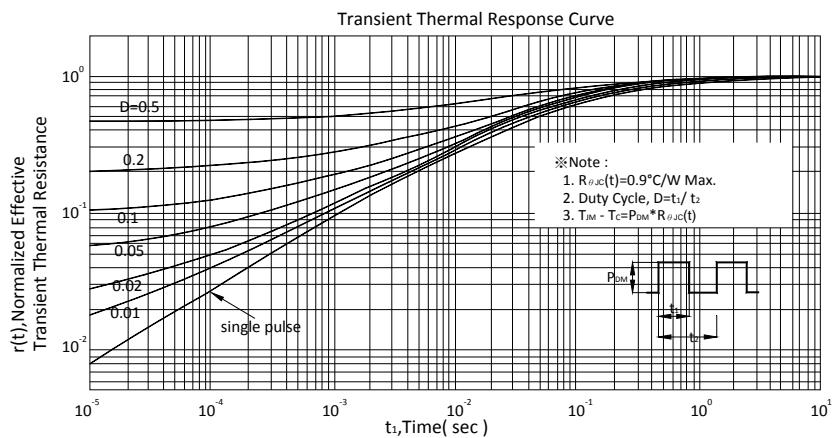
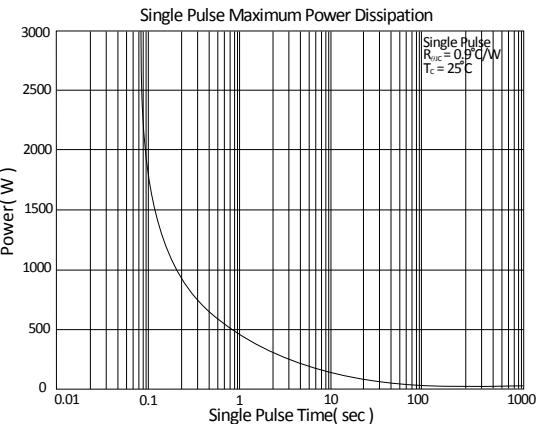
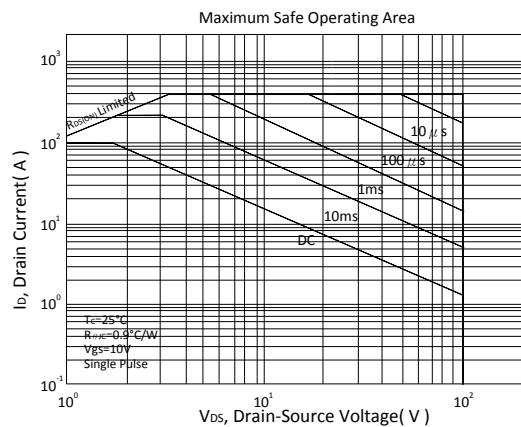
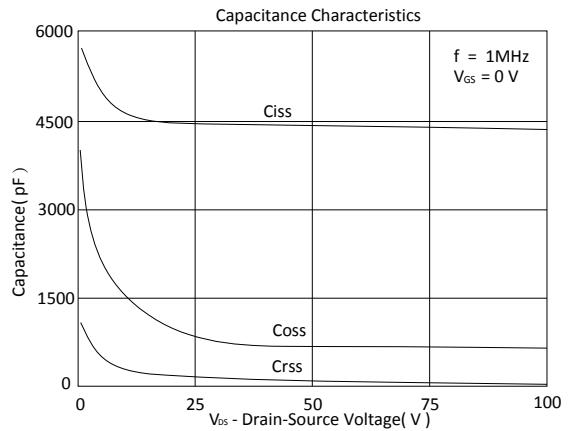
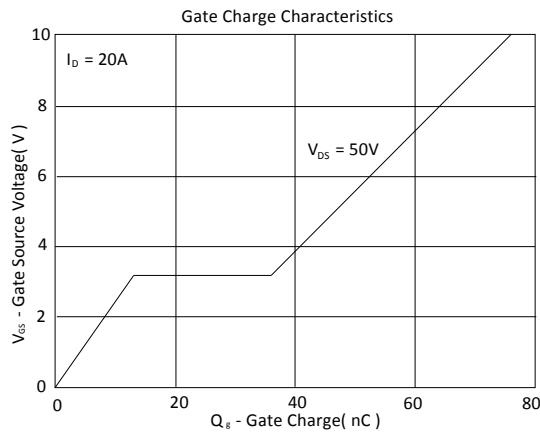
Ordering & Marking Information:

Device Name: LB85N10G for TO-220

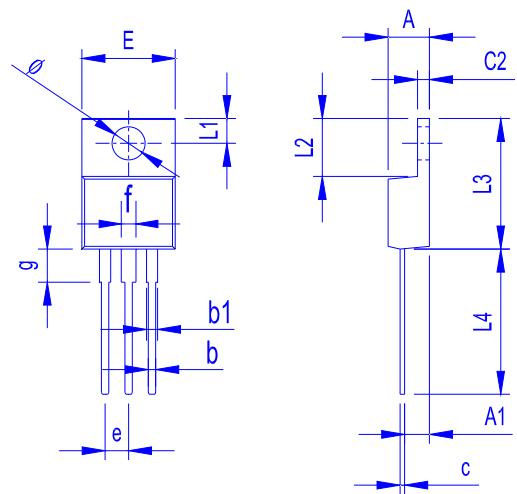


TYPICAL CHARACTERISTICS





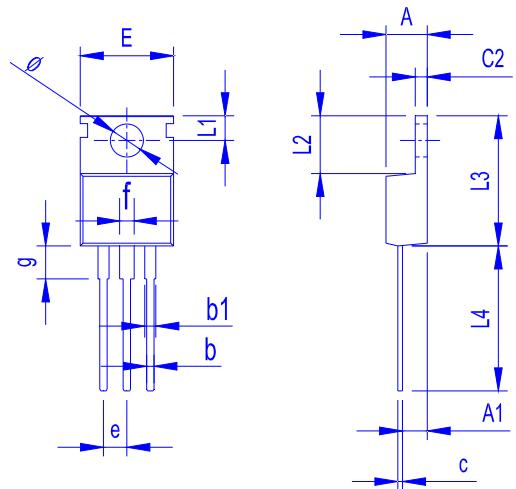
Outline Drawing A



Dimension in mm

Dimension	A	A1	b	b1	c	c2	E	L1	L2	L3	L4	ø	e	f	g
Min.	4.20	2.40	0.70	0.90	0.30	1.10	9.80	2.55	6.10	14.80	13.50	3.40	2.35	1.30	3.40
Max.	4.80	3.00	1.10	1.50	0.70	1.50	10.50	2.85	6.50	15.40	14.50	3.80	2.75	1.90	3.80

Outline Drawing B



Dimension in mm

Dimension	A	A1	b	b1	c	c2	E	L1	L2	L3	L4	ø	e	f	g
Min.	4.20	2.20	0.70	1.17	0.30	1.10	9.66	2.55	6.10	14.80	12.70	3.40	2.35	1.17	2.60
Max.	4.80	2.60	1.10	1.72	0.70	1.50	10.50	2.95	6.80	15.90	14.50	3.80	2.75	1.90	3.80